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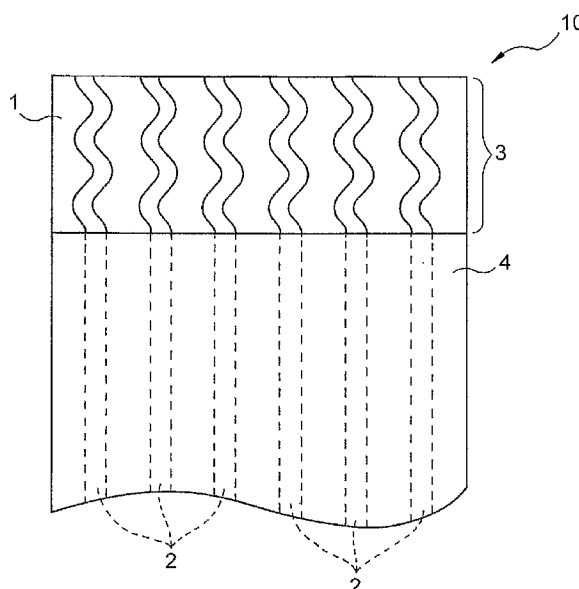
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(54) Title: METHOD FOR MUTUALLY CONNECTING CIRCUIT BOARDS



(57) Abstract: A method for connecting circuit boards, comprising: (i) preparing a first circuit board having connection parts assigned to end parts of a plurality of conductor wirings, and a second circuit board having connection parts assigned to corresponding end parts of a plurality of conductor wirings; (ii) disposing the connection parts of the first circuit board to face the connection parts of the second circuit board with a thermosetting adhesive film between the connection parts of the circuit boards; and (iii) applying heat and pressure to the connection parts and to the thermosetting adhesive film sufficiently high to thoroughly push away the adhesive film so as to establish electrical contact between connection parts of the circuit boards facing each other and to allow for curing of the adhesive; wherein the conductor wirings constituting the connection parts of at least one of the first and second circuit boards contain non-linear wirings.

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